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FT0407MH00TU

ΕN

This Datasheet is presented by the manufacturer

DE

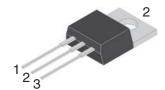
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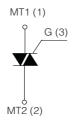
FR

Cette fiche technique est présentée par le fabricant



TO-220AB





On-State Current

Gate Trigger Current

4 Amp

 \leq 10 mA

Off-State Voltage

400 V ÷ 800 V

FEATURES

- Glass/passivated die junctions
- Medium current Triac
- Ideal for automated placement
- Low thermal resistance
- High surge current capability
- Low forward voltage drop
- Solder dip 260°C, 10s
- Component in accordance to RoHS 2011/65/EU and WEEE 2002/96/EC
- Meets MSL level 3, per J-STD-020, LF maximum peak of 260° C

MECHANICAL DATA

- Case: TO-220AB. Epoxy meets UL 94V-0 flammability rating.
- **Polarity:** As marked on the body.
- **Terminals:** Matte tin plated leads, solderable per MIL-STD-750 Method 2026, J-STD-002 and JESD22-B102. Consumer grade, meets JESD 201 class 1A whisker test.

TYPICAL APPLICATIONS

Logic level versions are designed to interface directly with low power drivers such as microcontrollers.

Maximun Ratings and Electrical Characteristics at 25°C

SYMBOL	PARAMETER	CONDITIONS	Value	Unit
I _{T(RMS)}	RMS On-state Current (full sine wave)	All Conduction Angle, T _c =95 °C	4	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 60 Hz (t = 16.7 ms)	33	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 50 Hz (t = 20 ms)	30	А
I ² t	Fusing Current	tp = 10 ms, Half Cycle	4.5	A ² s
I _{GM}	Peak Gate Current	20 μs max. Tj = 125 °C	4	А
P _{G(AV)}	Average Gate Power Dissipation	Tj = 125 °C	1	W
dI/dt	Critical rate of rise of on-state current	$I_G = 2x I_{GT}, t_r \le 100 \text{ns}$	50	A/µs
		f = 120 Hz, T _j = 125 °C		
T _j	Operating Temperature		(-40 +125)	°C
T _{stg}	Storage Temperature		(-40 +150)	°C
T _{sld}	Soldering Temperature	10s max	260	°C

SYMBOL	PARAMETER		Unit			
OTWIBOL	T / W / WIETER	D	M	N	Offic	
V_{DRM}/V_{RRM}	Repetitive Peak Off State Voltage	400	600	800	V	

Revision: 1

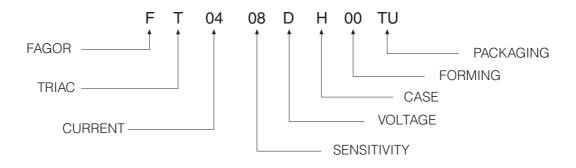


Electrical Characteristics at Tamb = 25 °C

SYMBOL	PARAMETER	CONDITIONS		Quadrant		SENSITIVITY				Unit	
OTIVIDOL		CONDITIONS	,	Quadrant		04	05	07	08	09	Offic
I _{GT (1)}	Gate Trigger Current	$V_D = 12 V_{DC}, R_L = 33\Omega,$	$T_j = 25 ^{\circ}C$	Q1÷Q3	MAX	5	5	5	10	10	mA
				Q4	MAX		5	7		10	mΑ
V _{GT}	Gate Trigger Voltage	$V_D = 12 V_{DC}, R_L = 33\Omega,$	$T_j = 25 ^{\circ}C$	Q1÷Q3	MAX			1.3			V
				Q1÷Q4	MAX			1.3			V
V _{GD}	Gate Non Trigger Voltage	$V_D = V_{DRM}, R_L = 3.3 \text{ K}\Omega,$	$T_j = 125 ^{\circ}C$	Q1÷Q3	MIN			0.2			V
				Q1÷Q4	MIN			0.2			V
I _H ⁽²⁾	Holding Current	$I_T = 100 \text{ mA}$, Gate open	$T_j = 25 ^{\circ}C$		MAX	10	10	15	15	20	mA
I _L	Latching Current	$I_{G} = 1.2 I_{GT}, T_{j} = 25 ^{\circ}\text{C}$		Q1,Q3	MAX	10			25		mΑ
				Q1,Q3,Q4	MAX		10	20		20	mΑ
				Q2	MAX	20	20	30	30	25	mA
dV/dt ⁽²⁾	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}$, Gate of	open		MIN	20	20	20	40	40	V/µs
		$T_j = 125 ^{\circ}\text{C}$									
(dl/dt)c (2)	Critical Rate of Current Rise	$(dv/dt)c = 0.1 V/\mu s$	$T_j = 125 ^{\circ}C$		MIN	1.8	1.8	1.8	2.7	2.5	A/ms
		$(dv/dt)c = 10 V/\mu s$	$T_j = 125 ^{\circ}C$		MIN	0.9	0.9	0.9	2.0	1.5	A/ms
		without snubber	$T_j = 125 ^{\circ}\text{C}$		MIN	-	-	-	-	-	
V _{TM} ⁽²⁾	On-state Voltage	$I_T = 5.5 \text{ Amp, tp} = 380 \ \mu \text{s}$	s, $T_j = 25 ^{\circ}\text{C}$		MAX			1.6			V
V _{t (o)} (2)	Threshold Voltage	$T_j = 125 ^{\circ}\text{C}$			MAX			0.9			V
r _d ⁽²⁾	Dynamic resistance	$T_j = 125 ^{\circ}\text{C}$			MAX	120			mΩ		
I _{DRM} /I _{RRM}	Off-State Leakage Current	$V_D = V_{DRM}$,	$T_j = 125 ^{\circ}C$		MAX			0.5			mΑ
		$V_R = V_{RRM}$,	$T_j = 25 ^{\circ}C$		MAX			5			μΑ
R _{th(j-c)}	Thermal Resistance	for AC 360° conduction	angle					2.0			°C/W
	Junction-Case										
R _{th(j-a)}	Thermal Resistance										
	Junction-Ambient	$S = 1 \text{ cm}^2$						60			°C/W

⁽¹⁾ Minimum $I_{\mbox{\scriptsize GT}}$ is guaranted at 5% of $I_{\mbox{\scriptsize GT}}$ max.

Part Number Information



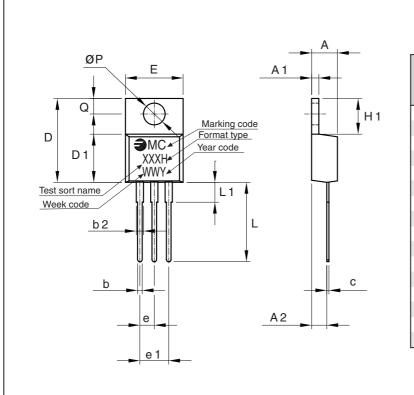
⁽²⁾ For either polarity of electrode MT2 voltage with reference to electrode MT1.



Ordering information

PREFERRED P/N	PACKAGE CODE	DELIVERY MODE	BASE QUANTITY	UNIT WEIGHT (g)
FT0408MH 00TU TU		TUBE	1,000	2.30

Package Outline Dimensions: (mm) TO-220AB



	DIMENSIONS				
REF.	Milimeters				
	Min.	Max.			
А	4.47	4.67			
A1	1.17	1.37			
A2	2.52	2.82			
b	0.71	0.91			
b2	1.17	1.37			
С	0.31	0.53			
D	14.65	15.35			
D1	8.50	8.90			
Ε	10.01	10.36			
е	2.51	2.57			
e1	4.98	5.18			
H1	6.15	6.45			
L	13.40	13.96			
L1	3.56	3.96			
Р	3.735	3.935			
Q	2.59	2.89			

Mounting Torque 0.8 N.m



Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle).

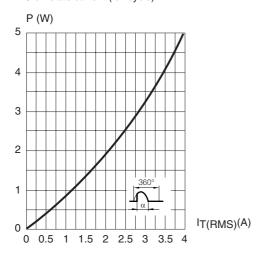


Fig. 3: Relative variation of thermal impedance versus pulse duration.

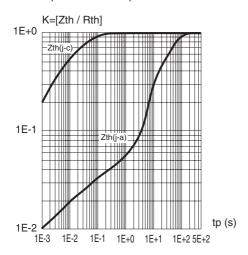


Fig. 5: Surge peak on-state current versus number of cycles

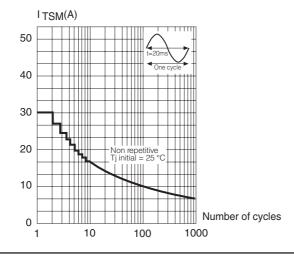


Fig. 2: RMS on-state current versus case temperature (full cycle).

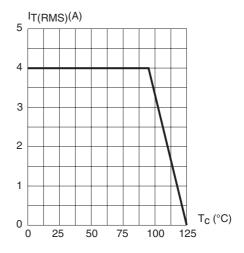


Fig. 4: On-state characteristics (maximum values)

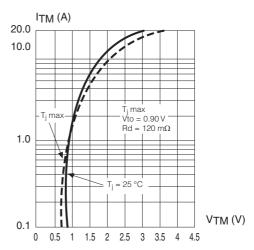
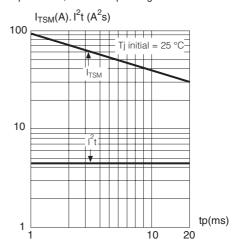


Fig. 6: Non repetitive surge peak on-state current for a sinusoidal pulse with width: tp < 10 ms, and corresponding value of I²t.





Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 7: Relative variation of gate trigger current, holding current and latching versus junction temperature (typical values)

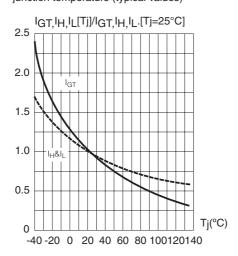


Fig. 9: Relative variation of critical rate of decrease of main current versus

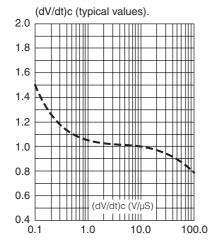
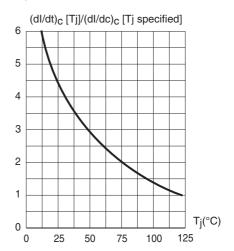


Fig. 8: Relative variation of critical rate of decrease of main current versus junction temperature





Revision History

Date Revision		Description of Changes			
14-Jun-2011 0		Original Data Sheet			
10-Mar-2015 1		200V and 700V eliminated			

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